# Baimei Tan

List of Publications by Year
in descending order

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| 35 | 425 | 13 | 19 |
|---|---|---|---|
| papers | citations | h-index | g-index |
| | | 687363 | 794594 |

| 35 | 35 | 35 | 208 |
|---|---|---|---|
| all docs | docs citations | times ranked | citing authors |

| # | Article | IF | Citations |
|---|---|---|---|
| 1 | Unraveling the Mechanism of Removing NA Contamination by TMAH-Based Cleaning Solution During Post Co-CMP Cleaning. ECS Journal of Solid State Science and Technology, 2022, 11, 034005. | 1.8 | 1 |
| 2 | Effect of Corrosion Inhibitor BTA on Silica Particles and their Adsorption on Copper Surface in Copper Interconnection CMP. ECS Journal of Solid State Science and Technology, 2022, 11, 044002. | 1.8 | 8 |
| 3 | Composite complex agent based on organic amine alkali for BTA removal in post CMP cleaning of copper interconnection. Journal of Electroanalytical Chemistry, 2022, 910, 116187. | 3.8 | 7 |
| 4 | Corrosion inhibitors for Cu chemical mechanical planarization (CMP). , 2022, , 155-170. | | 0 |
| 5 | The effect of structural properties of benzo derivative on the inhibition performance for copper corrosion in alkaline medium: Experimental and theoretical investigations. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2022, 649, 129531. | 4.7 | 15 |
| 6 | Synergistic effect of LABSA/JFCE combined surfactant system on the removal of particles on copper wafer surface. Materials Chemistry and Physics, 2021, 257, 123841. | 4.0 | 12 |
| 7 | Experimental validation and molecular dynamics simulation of removal of PO residue on Co surface by alkaline cleaning solution with different functional groups. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2021, 610, 125932. | 4.7 | 19 |
| 8 | Toward Understanding the Adsorption And Inhibition Mechanism of Cu-MBTA Passivation Film on Copper Surface: A Combined Experimental and DFT Investigation. Electronic Materials Letters, 2021, 17, 109-118. | 2.2 | 18 |
| 9 | Adsorption Mechanism of Potassium Oleate on Cobalt Surface Based on Cobalt Interconnection CMP: A Combined Experimental and DFT Investigation. ECS Journal of Solid State Science and Technology, 2021, 10, 024003. | 1.8 | 11 |
| 10 | Removal of Nanoceria Abrasive Particles by Using Diluted SC1 and Non-Ionic Surfactant. ECS Journal of Solid State Science and Technology, 2021, 10, 034010. | 1.8 | 5 |
| 11 | Effect of EDTA-based alkaline cleaning solution on TAZ removal in post CMP cleaning of copper interconnection. Materials Research Bulletin, 2021, 137, 111202. | 5.2 | 10 |
| 12 | Effect of Intermolecular Interaction of Compound Surfactant on Particle Removal in Post-Cu CMP Cleaning. ECS Journal of Solid State Science and Technology, 2021, 10, 064007. | 1.8 | 5 |
| 13 | Multidimensional insights into the corrosion inhibition of potassium oleate on Cu in alkaline medium: A combined Experimental and theoretical investigation. Materials Science and Engineering B: Solid-State Materials for Advanced Technology, 2021, 272, 115330. | 3.5 | 15 |
| 14 | Influence of diamond wire saw slicing parameters on (010) lattice plane beta-gallium oxide single crystal wafer. Materials Science in Semiconductor Processing, 2021, 133, 105939. | 4.0 | 4 |
| 15 | Theoretical and electrochemical analysis on inhibition effects of benzotriazole derivatives (un- and) Tj ETQq1 1 0.784314 rgBT /Overlock | 3.6 | 16 |
| 16 | Unraveling the surface behavior of amino acids on Cu wiring in chemical mechanical polishing of barrier layers: A combination of experiments and ReaxFF MD. Journal of Molecular Liquids, 2021, 341, 117307. | 4.9 | 10 |
| 17 | Effect of ethylenediamine on CMP performance of ruthenium in H<sub>2</sub>O<sub>2</sub>-based slurries. RSC Advances, 2021, 12, 228-240. | 3.6 | 6 |
| 18 | Effect of arginine-based cleaning solution on BTA residue removal after Cu-CMP. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2020, 586, 124286. | 4.7 | 36 |

| # | Article | IF | Citations |
|---|---|---|---|
| 19 | Corrosion control of copper wiring by barrier CMP slurry containing azole inhibitor: Combination of simulation and experiment. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2020, 599, 124872. | 4.7 | 44 |
| 20 | Theoretical and electrochemical analysis on inhibition effect of benzotriazole and 1,2,4-triazole on cobalt surface. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2020, 591, 124516. | 4.7 | 28 |
| 21 | Synergistic effect of composite complex agent on BTA removal in post CMP cleaning of copper interconnection. Materials Chemistry and Physics, 2020, 252, 123230. | 4.0 | 27 |
| 22 | Synergetic Effect of 5-Methyl-1H-Benzotriazole and Sodium Dodecyl Benzene Sulfonate on CMP Performance of Ruthenium Barrier Layer in KIO<sub>4</sub>-Based Slurry. ECS Journal of Solid State Science and Technology, 2020, 9, 104005. | 1.8 | 6 |
| 23 | Study on Different Surfactants for Post CMP Cleaning of Novel Barrier. , 2019, , . | | 1 |
| 24 | Study on Infrared Spectrum Detection and Analysis of BTA Residual after Copper CMP. , 2019, , . | | 0 |
| 25 | Effects of Novel Inhibitor on Galvanic Corrosion of Copper and Cobalt and Particle Removal. ECS Journal of Solid State Science and Technology, 2019, 8, P545-P552. | 1.8 | 11 |
| 26 | Study on the Adsorption and Inhibition Mechanism of 1,2,4-Triazole on Copper Surface in Copper Interconnection CMP. ECS Journal of Solid State Science and Technology, 2019, 8, P313-P318. | 1.8 | 15 |
| 27 | A study of FTIR and XPS analysis of alkalineâ€based cleaning agent for removing Cuâ€BTA residue on Cu wafer. Surface and Interface Analysis, 2019, 51, 566-575. | 1.8 | 28 |
| 28 | Optimization of cleaning process parameters to remove abrasive particles in post-Cu CMP cleaning. Journal of Semiconductors, 2018, 39, 126002. | 3.7 | 4 |
| 29 | Effect of organic amine alkali and inorganic alkali on benzotriazole removal during post Cu-CMP cleaning. Journal of Semiconductors, 2018, 39, 126003. | 3.7 | 7 |
| 30 | Application of surfactant for facilitating benzotriazole removal and inhibiting copper corrosion during post-CMP cleaning. Microelectronic Engineering, 2018, 202, 1-8. | 2.4 | 24 |
| 31 | Role of Penetrating Agent on Colloidal Silica Particle Removal during Post Cu CMP Cleaning. ECS Journal of Solid State Science and Technology, 2018, 7, P380-P384. | 1.8 | 9 |
| 32 | Thermal Stability Study of GaP/Highâ€<i>k</i> Dielectrics Interfaces. Advanced Materials Interfaces, 2017, 4, 1700609. | 3.7 | 5 |
| 33 | A novel cleaner for colloidal silica abrasive removal in post-Cu CMP cleaning. Journal of Semiconductors, 2015, 36, 106002. | 3.7 | 5 |
| 34 | Non-ionic surfactant on particles removal in post-CMP cleaning. Journal of Semiconductors, 2015, 36, 026002. | 3.7 | 13 |
| 35 | Eco-friendly Corrosion Inhibitors for Multilevel Metal Interconnects of Integrated Circuits. ACS Symposium Series, 0, , 149-165. | 0.5 | 0 |